

Dicing 신규 장비 Business Concept



Development & Production

Core technology

- ◆ For 12inch Si wafer
- ◆ Repeatability accuracy (Y-axis) : 0.0005
- ◆ Efficiency
 - 1.2 ~ 2.4kw Air spindle
 - Max. spindle revolutions : 60,000rpm
 - Blade size : 60(for 2" blade)
 - Rotation angle : DD SERVO 380(CW/CCW)
 - Cutting speed : 0.05 ~ 700mm/sec
- ◆ Vacuum chuck : convertible(6~12inch)
- ◆ Application : Si wafer, Ceramic, Quartz, LED, Ar/Blue glass filter, etc

Semi Automatic type

Model : FSS-12NB



Dicing 신규 장비



Development & Production

Fully Automatic type

Model : FSF-12NB



Core technology

- ◆ For 12inch Si wafer
- ◆ Repeatability accuracy (Y-axis) : 0.0005
- ◆ Efficiency
 - 1.2 ~ 2.4kw Air spindle x 2sets, Facing dual spindle
 - Max. spindle revolutions : 60,000rpm
 - Blade size : 60(for 2" blade)
 - Rotation angle : DD SERVO 380(CW/CCW)
 - Cutting speed : 0.05 ~ 650mm/sec
- ◆ Vacuum chuck : convertible(6~12inch)
- ◆ Application : Si wafer, Ceramic, Quartz,
LED, Ar/Blue glass filter,
GaAs, SiGe, etc.

Dicing 신규 장비



Differentiation key features

Div.	FST (FSF-12NB)	DISCO (DFD6361)
Alignment	Multi method	Single method
Repeatability Accuracy (Y-axis)	0.0005	0.001
Blade abrasion Reduction Func.	YES	NO
Configuration separation cutting of wafer	YES	NO
Cutting speed	Max. 650mm/sec	Max. 600mm/sec

Dicing 신규 장비

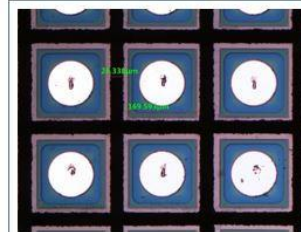


Cutting examples

Core competency

- ◆ **Si wafer** – Iris recognition sensor
 - Chip size : $190\mu\text{m} \times 190\mu\text{m}$, Kerf size : $30\mu\text{m}$
 - Company : Raytopia co., Ltd. Korea
- ◆ **Ceramic wafer** – Automotive sensor
 - Chip size : $950\mu\text{m} \times 950\mu\text{m}$
 - company : TSP co., Ltd. Korea
- ◆ **Chip LED**
 - Chip size : $2\text{mm} \times 2\text{mm}$
 - company : MLS , China
- ◆ **Silicon 0.5t soft film** – LED fluorescent body
 - Chip size : $1\text{mm} \times 1\text{mm}$
 - company : Seoul viosys , Korea

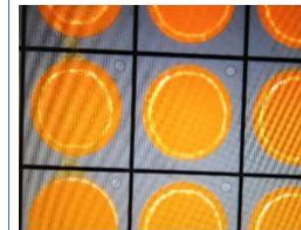
Process results



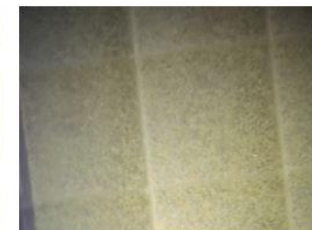
Si wafer



Ceramic wafer



Chip LED – Si wafer



LED – 0.5t film/soft Si

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Cutting examples (contd.)

Core competency

◆ AR/Blue Glass filter – Mobile camera

- Chip size : 5mm x 5mm , Thickness : 1t
- Company : Optrontec, Korea

◆ LED Lead Frame – MC material

- Chip size : 5mm x 5mm
- company : Lumens, China factory

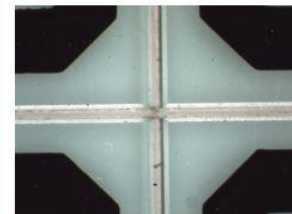
◆ Si wafer – Memory device

- Chip size : 5mm x 5mm
- company : ASE Taiwan

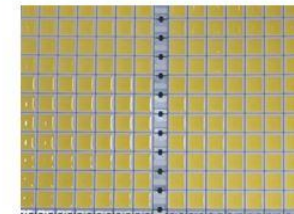
◆ CCD – Charged Coupled Device

- Chip size : 10mm x 10mm
- company : Terrasem Inc. , Korea

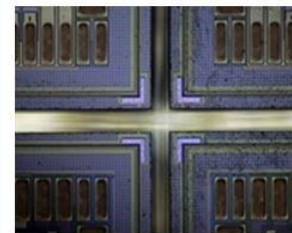
Process results



AR/ blue Glass filter



LED-MC L/F



Si wafer



CCD Device

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Accessories & Consumables

Facilities



Spin Cleaner



Tape Mounter

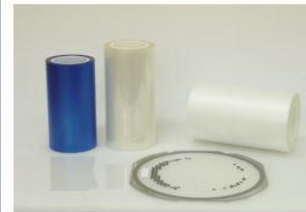


UV Irradiator



DI water chilling system

Consumables



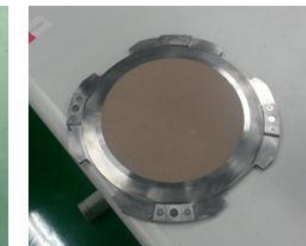
Dicing Tape



Dicing Blades

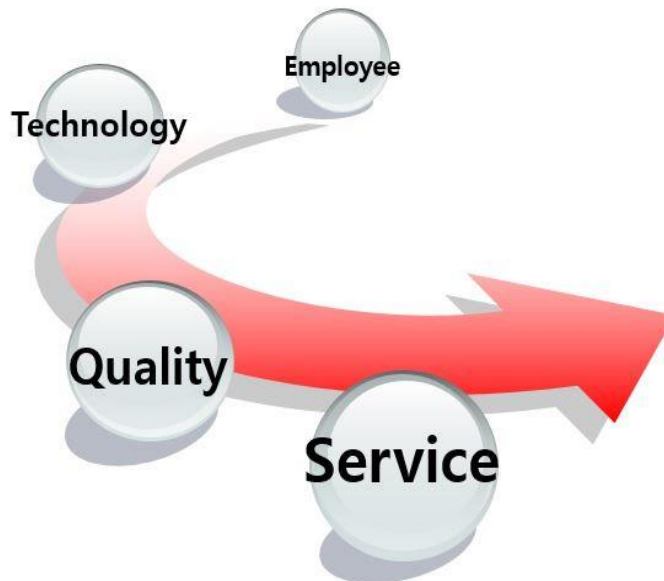


Ring Frame & Cassette



Vacuum Chuck

Dicing 신규 장비



... to the customer.

Pioneering valuable propositions

in the field of : Semiconductor

FPD

LED

PCB

Distribution

Service

Dicing 신규 장비

작업 순서 및 준비 체크 사항



Confirmation of
State

Concept
Discussion

Amount
Negotiation

P/O receive



make
beginning

“ Check List 작성을 위해 클릭 하기 ”

팝업창이 나오면 “허용”, “예” 를 차례로 눌러주세요

Dicing 신규 장비



축전 된 기술과 경험으로, 사용하시기 편리한 신규 장비를 제작해
드립니다. **작업 효율성**과 **성능**에서
대 만족하실 것을 확신 드립니다.
감사합니다.

2017년 주식 회사 **바 이 세 미** 배 상

WITH CUSTOMER , FOR CUSTOMER !!